

Dual Voltage Detector with Adjustable Hysteresis

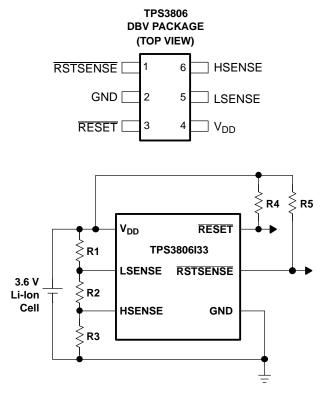
FEATURES

- Dual Voltage Detector With Adjustable Hysteresis 3.3-V/Adjustable and 2-V/Adjustable
- Assured Reset at V_{DD} = 0.8 V
- Supply Current: 3 μA Typical at V_{DD} = 3.3 V
- Independent Open-Drain Reset Outputs
- Temperature Range: -40°C to +85°C
- 6-Pin SOT-23 Package

DESCRIPTION

The TPS3806 integrates two independent voltage detectors for battery voltage monitoring. During power-on, RESET and RSTSENSE are asserted when supply voltage V_{DD} or the voltage at LSENSE input become higher than 0.8 V. Thereafter, the supervisory circuit monitors VDD and LSENSE, keeping RESET and RSTSENSE active as long as V_{DD} and LSENSE remain below the threshold voltage, V_{IT}. As soon as V_{DD} or LSENSE rise above the threshold voltage V_{IT} , RESET or RSTSENSE is deasserted, respectively. The TPS3806 device has a fixed-sense threshold voltage VIT set by an internal voltage divider at V_{DD} and an adjustable second-LSENSE input. In addition, an upper voltage threshold can be set at **HSENSE** to allow wide adjustable а hysteresis window.

The devices are available in a 6-pin SOT-23 package. The TPS3806 device is characterized for operation over a temperature range of -40°C to +85°C.



Typical Operating Circuit



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.





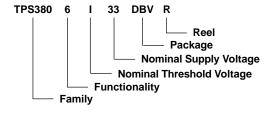
This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION(1)

т	DEVICE	- NAME	THRESHOL	D VOLTAGE	MARKING
IA	DEVICE	ENAME	V _{DD}	SENSE	WARKING
40°C to 195°C	TPS3806J20DBVR ⁽²⁾	TPS3806J20DBVT ⁽³⁾	1.8 V	1.207 V	PGQI
-40°C to +85°C	TPS3806I33DBVR ⁽²⁾	TPS3806I33DBVT ⁽³⁾	3 V	1.207 V	PGPI

- (1) For the most current package and ordering information, see the Package Option Addendum located at the end of this data sheet or refer to our web site at www.ti.com.
- (2) The DBVR passive indicates tape and reel containing 3000 parts.
- (3) The DBVT passive indicates tape and reel containing 250 parts.



ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)(1)

	TPS3806J20, TPS3806I33	UNIT
Supply voltage, V _{DD} ⁽²⁾	7	V
All other pins ⁽²⁾	-0.3 to 7	V
Maximum low-output current, I _{OL}	5	mA
Maximum high-output current, I _{OH}	-5	mA
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{DD})	±10	mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{DD})	±10	mA
Continuous total power dissipation	See Dissipation Rating Table	
Operating free-air temperature range, T _A	-40 to +85	°C
Storage temperature range, T _{stg}	-65 to +150	°C
Soldering temperature	+260	°C

⁽¹⁾ Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

PACKAGE	T _A < 25°C	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING
DBV	437 mW	3.5 mW/°C	280 mW	227 mW

⁽²⁾ All voltage values are with respect to GND. For reliable operation, the device must not be continuously operated at 7 V for more than t = 1000 h.



RECOMMENDED OPERATING CONDITIONS

	MIN	MAX	UNIT
Supply voltage, V _{DD}	1.3	6	٧
Input voltage, V _I	0	V _{DD} + 0.3	V
Operating free-air temperature range, T _A	-40	+85	°C

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARA	AMETER		MIN	TYP	MAX	UNIT	
			V _{DD} = 1.5 V, I _{OL} = 1 mA				
V_{OL}	Low-level output voltage	$V_{DD} = 3.3 \text{ V}, I_{OL} = 2 \text{ mA}$			0.3	V	
			V _{DD} = 6 V, I _{OL} = 3 mA				
	Power-up reset voltage ⁽¹⁾		$V_{DD} \ge 0.8 \text{ V}, I_{OL} = 50 \mu\text{A}$			0.2	V
		LSENSE		1.198	1.207	1.216	
	V _{IT} Negative-going input threshold voltage ⁽²⁾	TPS3806J20	$T_A = +25^{\circ}C$	1.787	1.8	1.813	V
		TPS3806I33		2.978	3.0	3.022	
		LSENSE		1.188	1.207	1.226	
V_{IT}		TPS3806J20	$T_A = 0$ °C to +70°C	1.772	1.8	1.828	V
	input unochola voltago	TPS3806I33		2.952	3.0	3.048	
		LSENSE		1.183	1.207	1.231	
		TPS3806J20 $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$		1.764	1.8	1.836	V
		TPS3806l33		2.94	3.0	3.06	
\/	Lhyotoropio	·	1.2 V < V _{IT} < 2.5 V		60		mV
V_{hys}	Hysteresis		2.5 V < V _{IT} < 3.5 V		90		mv
I	Input current	LSENSE, HSENSE		-25		25	nA
I_{OH}	High-level output current		$V_{DD} = V_{IT} + 0.2 \text{ V}, V_{OH} = V_{DD}$			300	nA
	Inn Supply current		V _{DD} = 3.3 V, Output unconnected		3	5	
IDD			V _{DD} = 6 V, Output unconnected		4	6	μΑ
Ci	Input capacitance		V _I = 0 V to V _{DD}		1		pF

SWITCHING CHARACTERISTICS

at R_L = 1 M Ω , C_L = 50 pF, T_A = -40°C to +85°C

PARA	METER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
	Propagation (delay) time,	V _{DD} to RESET delay			E	100	
ι _{PHL}	high-to-low-level output	LSENSE to RSTSENSE delay	$V_{IH} = 1.05 \times V_{IT}$		5	100	μs
	Propagation (delay) time,	V _{DD} to RESET delay	$V_{IL} = 0.95 \times V_{IT}$		-	100	
^T PLH	low-to-high-level output	HSENSE to RSTSENSE delay			Э	100	μs

TIMING REQUIREMENTS

at R_L = 1 M Ω , C_L = 50 pF, T_A = -40°C to +85°C

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
	Pulse width	At V _{DD}	V - 105 x V V - 0.05 x V	E			
ι _w	Fuise width	At SENSE	$V_{IH} = 1.05 \times V_{IT}, V_{IL} = 0.95 \times V_{IT}$	5.5			μs

 ⁽¹⁾ The lowest supply voltage at which RESET becomes active. t_{r,VDD} ≥ 15 μs/V
 (2) To ensure best stability of the threshold voltage, place a bypass capacitor (ceramic, 0.1 μF) near the supply terminals.



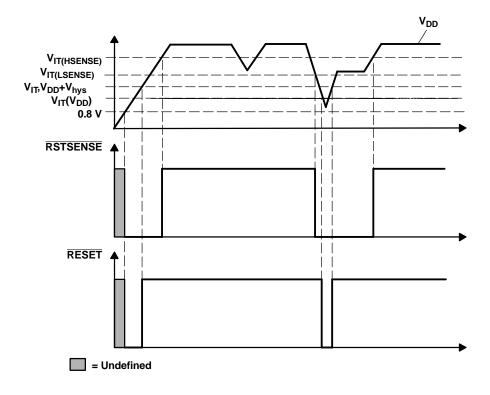


Table 1. TERMINAL FUNCTIONS

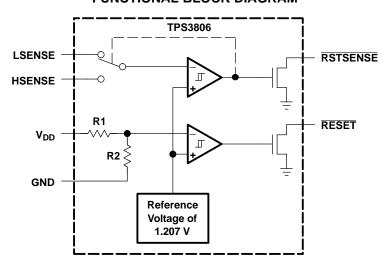
TERMINAL I/O		1/0	DESCRIPTION
		1/0	DESCRIPTION
GND	2	I	Ground
HSENSE	6	I	Adjustable hysteresis input
LSENSE	5	I	Adjustable sense input
RESET	3	0	Active-low open drain reset output (from V _{DD})
RSTSENSE	1	0	Active-low open-drain reset output (from LSENSE)
V_{DD}	4	I	Input supply voltage and fixed sense input

FUNCTION/TRUTH TABLE

TPS3806										
V _{DD} > V _{IT} RESET LSENSE > V _{IT} RSTSENSE										
0	L	0	L							
1	Н	1	Н							



FUNCTIONAL BLOCK DIAGRAM



Detailed Description

Operation

The TPS3806 is used for monitoring battery voltage and asserting $\overline{\text{RESET}}$ when a battery gets discharged below a certain threshold voltage. The battery voltage is monitored by a comparator via an external resistor divider. When the voltage at the LSENSE input drops below the internal reference voltage the $\overline{\text{RSTSENSE}}$ output pulls low. The output remains low until the battery is replaced, or recharged above a second higher trip-point, set at HSENSE. A second voltage can be monitored at V_{DD} . The independent $\overline{\text{RESET}}$ output pulls low when the voltage at V_{DD} drops below the fixed threshold voltage. Because the TPS3806 outputs are open-drain MOSFETs, most applications may require a pull-up resistor.

Programming the Threshold Voltage Levels

The low-voltage threshold at LSENSE is calculated according to Equation 1:

$$V_{(LSENSE)} = V_{ref} \left(\frac{R1 + R2 + R3}{R2 + R3} \right)$$
(1)

where $V_{ref} = 1.207 \text{ V}$

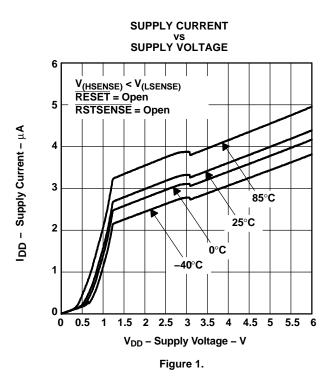
The high-voltage threshold at HSENSE is calculated as shown in Equation 2:

$$V_{(HSENSE)} = V_{ref} \left(\frac{R1 + R2 + R3}{R3} \right)$$
 (2)

where $V_{ref} = 1.207 \text{ V}$

To minimize battery current draw it is recommended to use 1-M Ω as the total resistor value $R_{(tot)}$, with $R_{(tot)} = R1 + R2 + R3$.

TYPICAL CHARACTERISTICS



LOW-LEVEL OUTPUT VOLTAGE vs LOW-LEVEL OUTPUT CURRENT

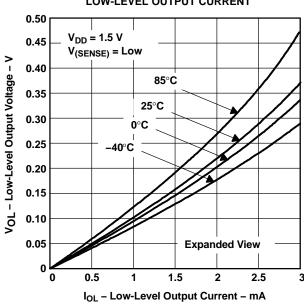
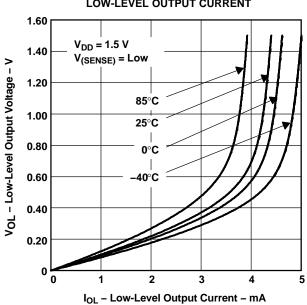


Figure 3.

LOW-LEVEL OUTPUT VOLTAGE vs LOW-LEVEL OUTPUT CURRENT



LOW-LEVEL OUTPUT VOLTAGE vs LOW-LEVEL OUTPUT CURRENT

Figure 2.

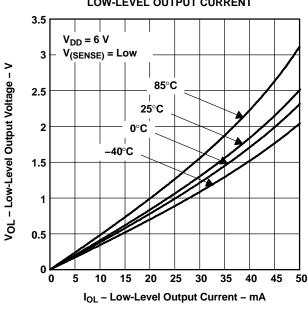


Figure 4.



TYPICAL CHARACTERISTICS (continued)

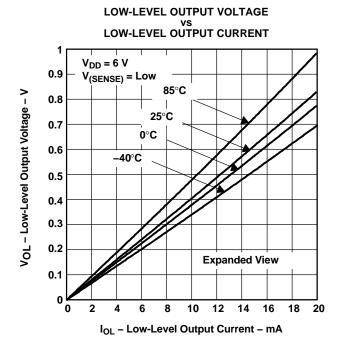
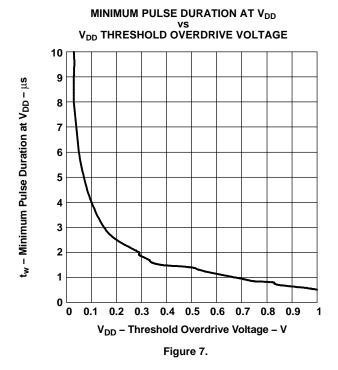


Figure 5.



NORMALIZED INPUT THRESHOLD VOLTAGE vs FREE-AIR TEMPERATURE AT VDD

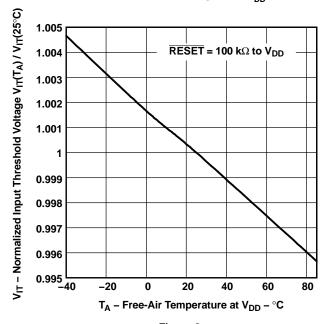
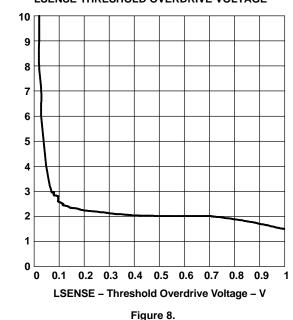


Figure 6.

MINIMUM PULSE DURATION AT LSENSE VS LSENSE THRESHOLD OVERDRIVE VOLTAGE



 t_w – Minimum Pulse Duration at LSENSE – μs

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TPS3806I33DBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3806l33DBVRG4	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3806l33DBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3806l33DBVTG4	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3806J20DBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3806J20DBVRG4	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3806J20DBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3806J20DBVTG4	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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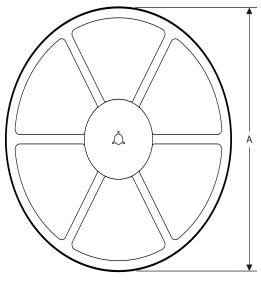
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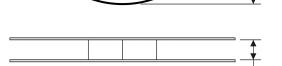
PACKAGE MATERIALS INFORMATION

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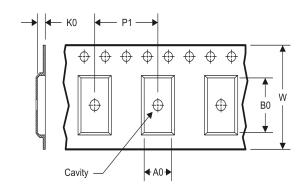
TAPE AND REEL INFORMATION

REEL DIMENSIONS





TAPE DIMENSIONS



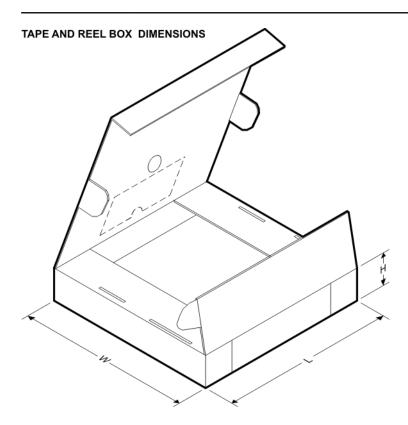
A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3806I33DBVR	SOT-23	DBV	6	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3806I33DBVR	SOT-23	DBV	6	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3806I33DBVT	SOT-23	DBV	6	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3806I33DBVT	SOT-23	DBV	6	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS3806J20DBVR	SOT-23	DBV	6	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3806J20DBVT	SOT-23	DBV	6	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3

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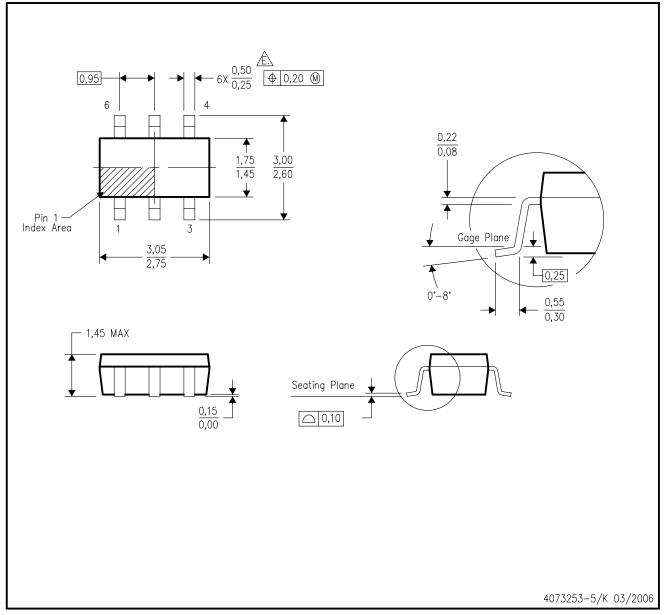


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3806I33DBVR	SOT-23	DBV	6	3000	203.0	203.0	35.0
TPS3806I33DBVR	SOT-23	DBV	6	3000	180.0	180.0	18.0
TPS3806I33DBVT	SOT-23	DBV	6	250	180.0	180.0	18.0
TPS3806I33DBVT	SOT-23	DBV	6	250	203.0	203.0	35.0
TPS3806J20DBVR	SOT-23	DBV	6	3000	180.0	180.0	18.0
TPS3806J20DBVT	SOT-23	DBV	6	250	180.0	180.0	18.0

DBV (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



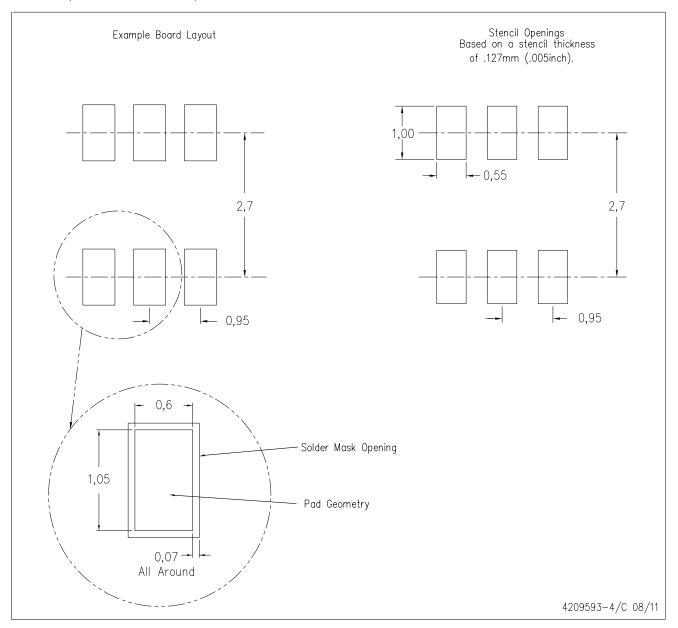
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
- Falls within JEDEC MO-178 Variation AB, except minimum lead width.



DBV (R-PDSO-G6)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



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- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001:
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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